



Click [here](#) for the 3D model.

Dimensions

Chip Size	0402
L	1.02mm +0.15/-0.1mm (0.04 in +0.006/-0.004 in)
W	0.51mm +0.13/-0.1mm (0.02 in +0.005/-0.004 in)
T	0.64mm MAX (0.025 in MAX)
B	0.1mm MIN (0.004 in MIN)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	368

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
Termination	Solder Plated
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	33 pF
Capacitance Tolerance	1%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)